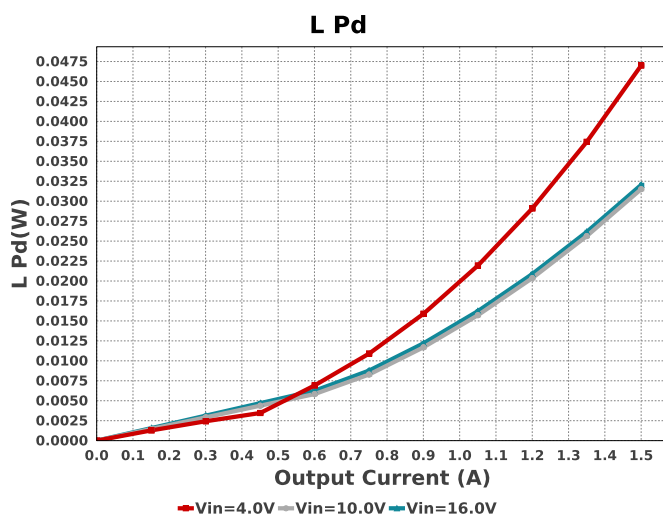
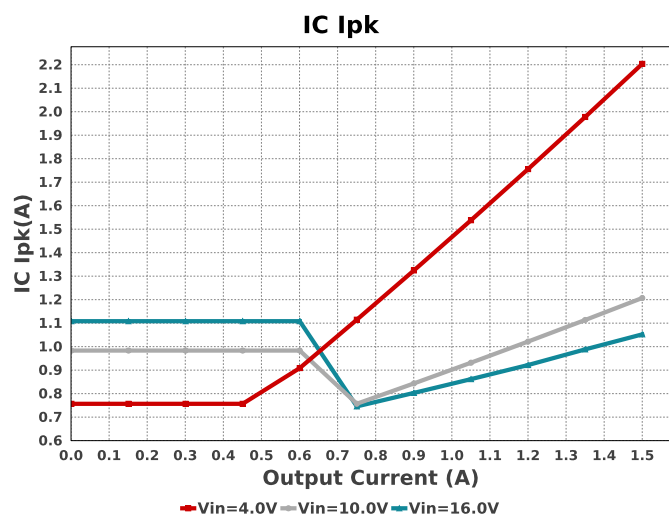
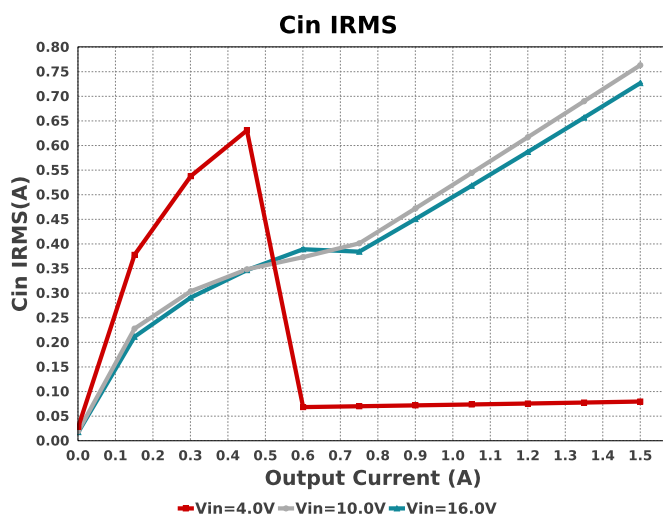
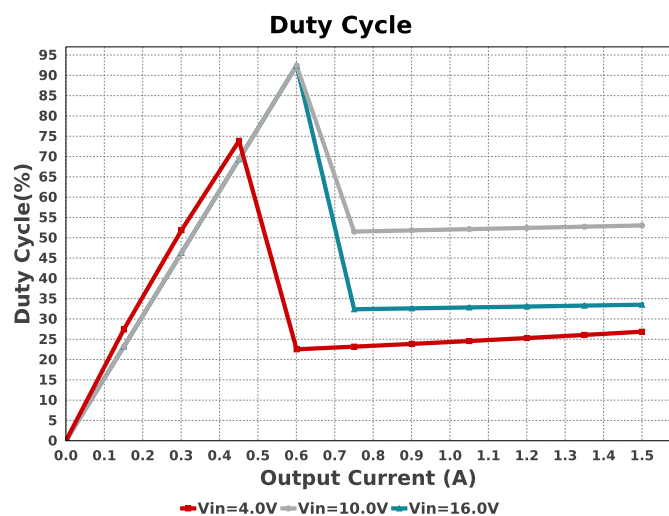
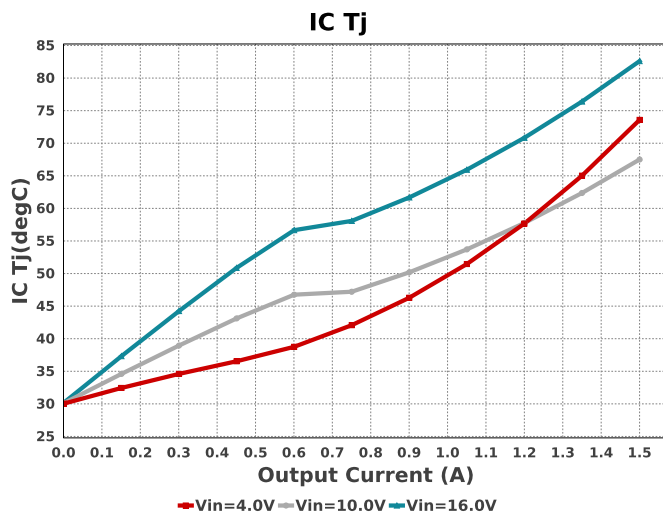
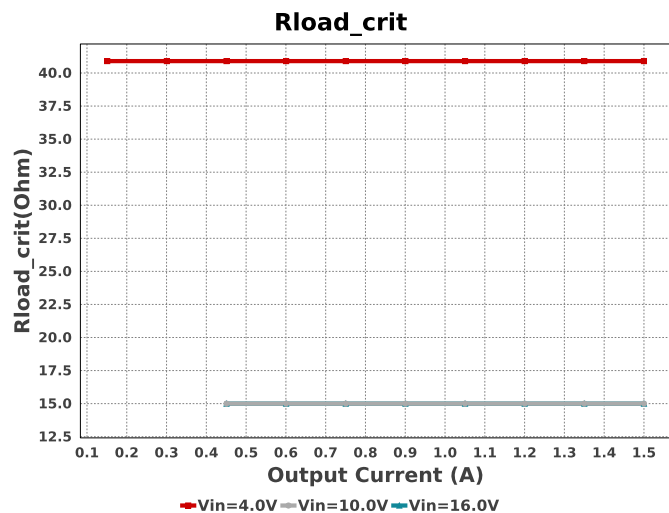
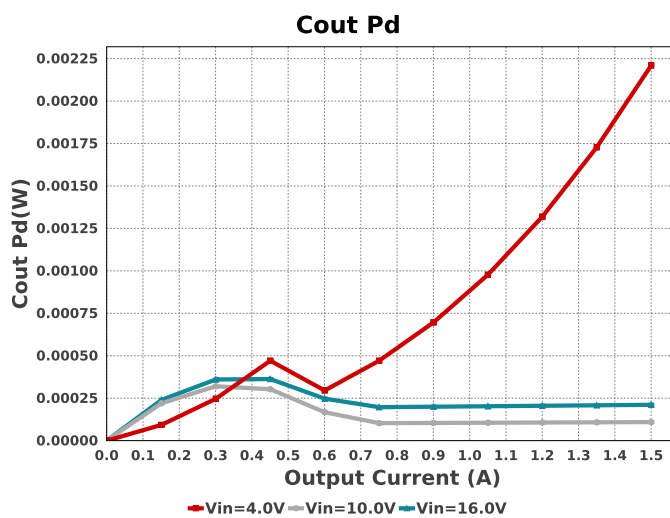
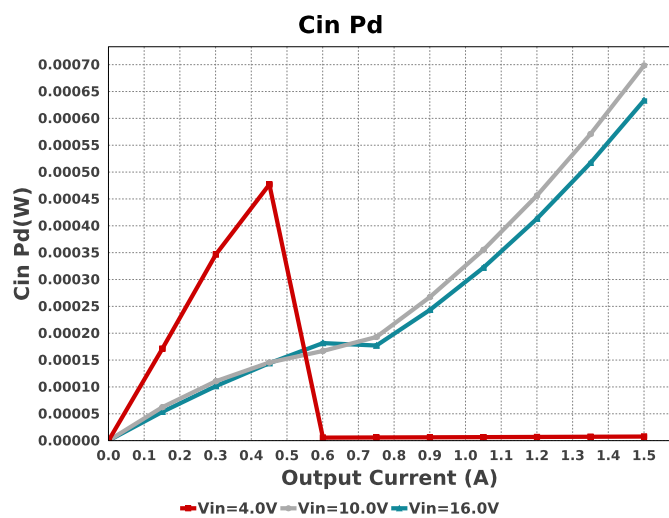
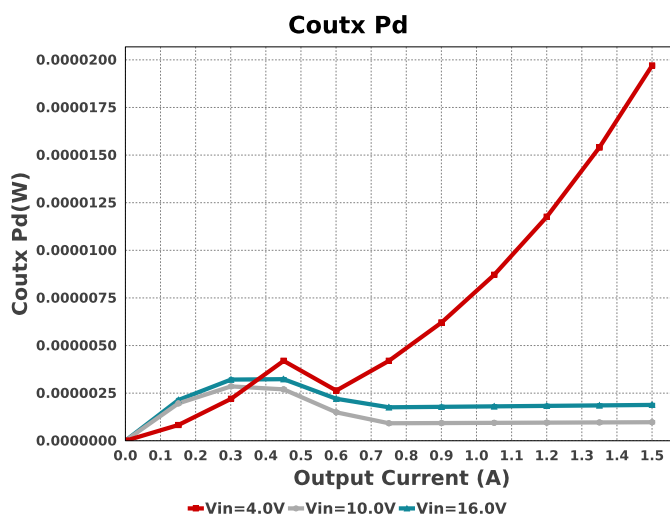
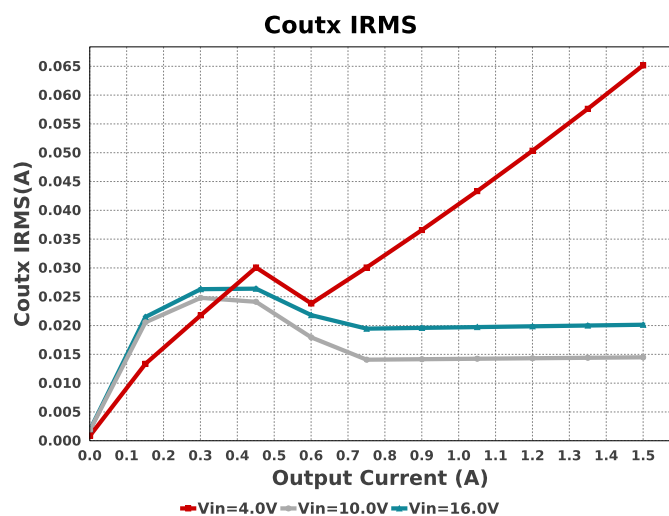
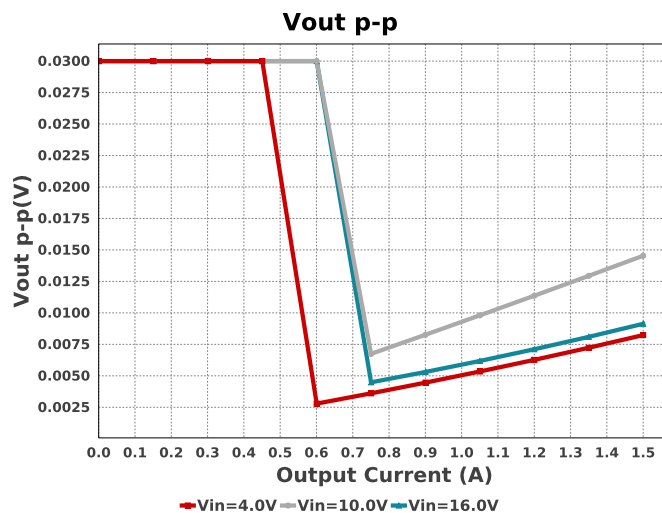
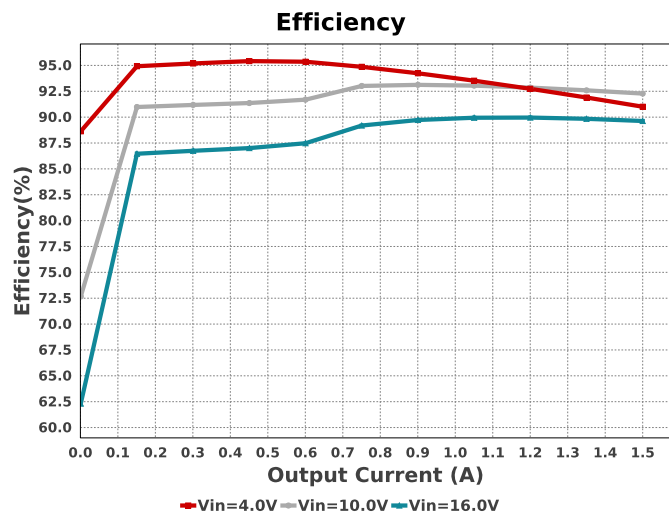
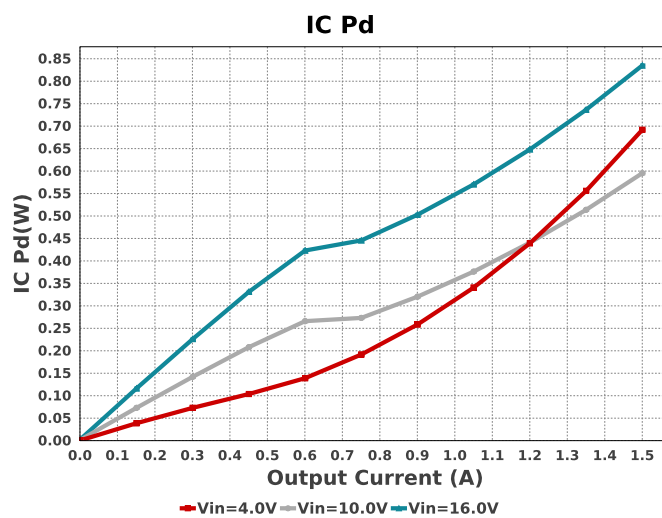
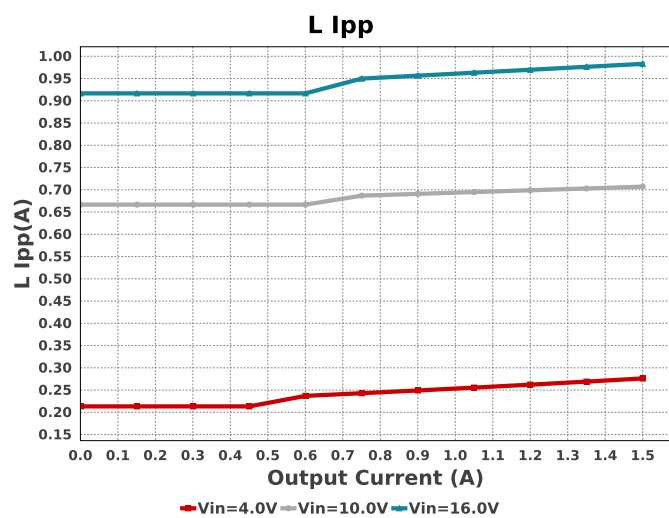
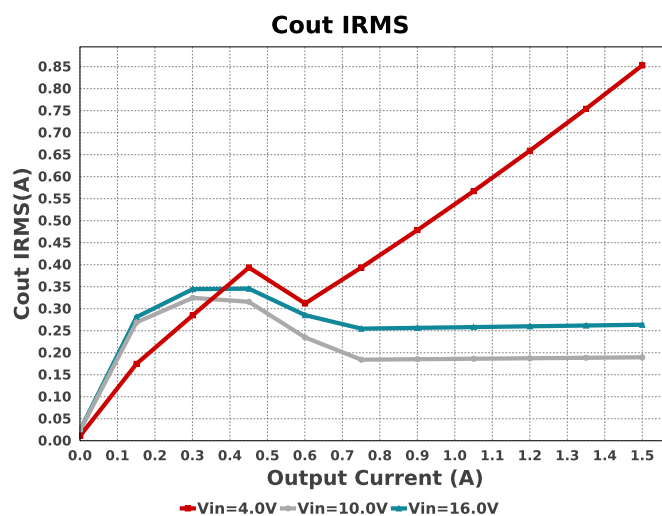
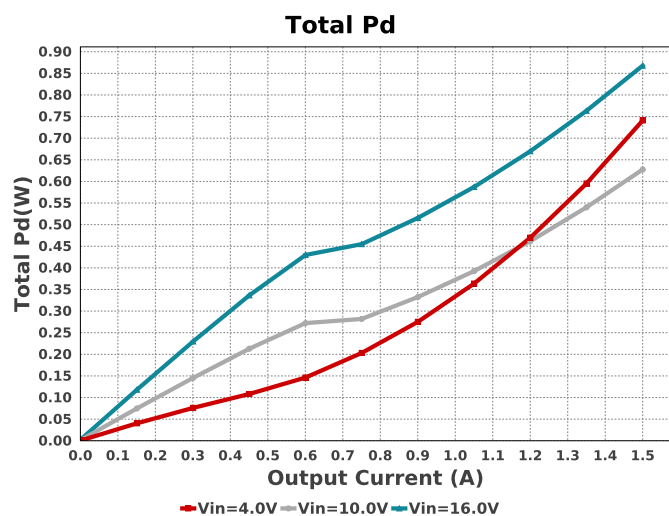
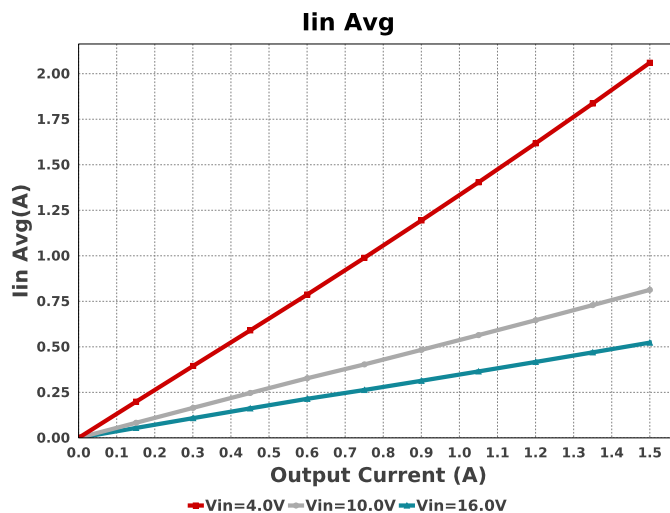
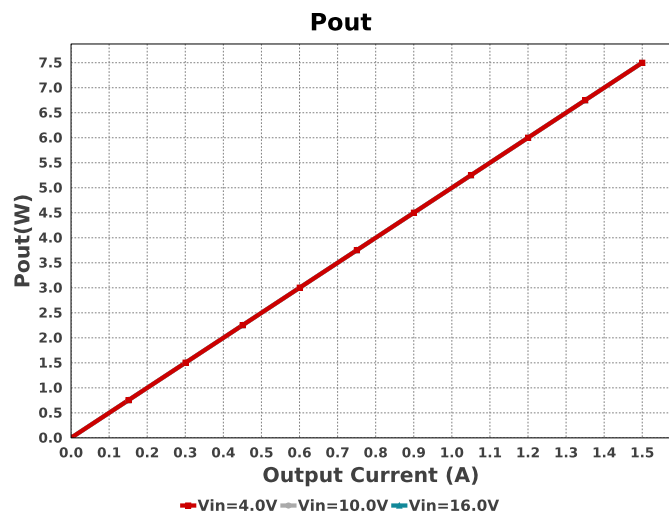


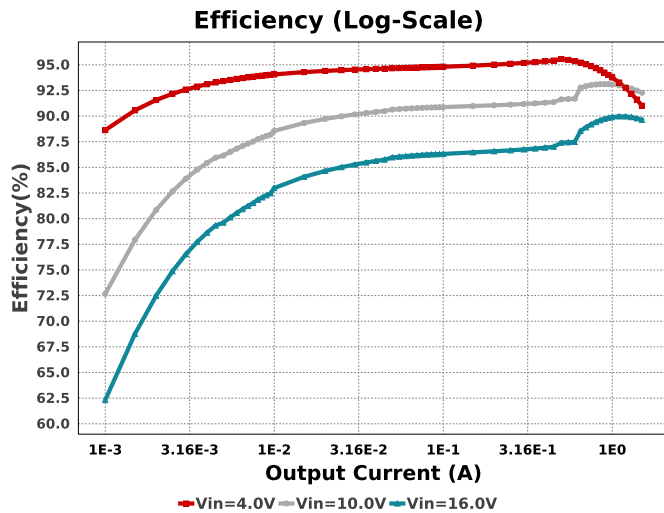


Device = TPS63070RNMNR  
Topology = Buck\_Boost  
Created = 2024-12-01 04:34:47.613  
BOM Cost = \$2.29  
BOM Count = 11  
Total Pd = 0.74W









## Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	79.706 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	7.617 $\mu$ W	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	852.693 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	0.0 W	Capacitor	Output capacitor power dissipation
5.	Coutx IRMS	65.142 mA	Capacitor	Output capacitor_x RMS ripple current
6.	Coutx Pd	0.0 W	Capacitor	Output capacitor_x power loss
7.	IC Ipk	2.203 A	IC	Peak switch current in IC
8.	IC Pd	691.41 mW	IC	IC power dissipation
9.	IC Tj	73.559 degC	IC	IC junction temperature
10.	ICThetaJA	63.0 degC/W	IC	IC junction-to-ambient thermal resistance
11.	Iin Avg	2.06 A	IC	Average input current
12.	L Ipp	276.11 mA	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	46.975 mW	Inductor	Inductor power dissipation
14.	Cin Pd	7.617 $\mu$ W	Power	Input capacitor power dissipation
15.	Cout Pd	0.0 W	Power	Output capacitor power dissipation
16.	Coutx Pd	0.0 W	Power	Output capacitor_x power loss
17.	IC Pd	691.41 mW	Power	IC power dissipation
18.	L Pd	46.975 mW	Power	Inductor power dissipation
19.	Total Pd	738.408 mW	Power	Total Power Dissipation
20.	BOM Count	11	System	Total Design BOM count
				Information
21.	Duty Cycle	26.859 %	System	Duty cycle
				Information
22.	Efficiency	91.037 %	System	Steady state efficiency
				Information
23.	FootPrint	174.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
				Information
24.	Frequency	2.5 MHz	System	Switching frequency
				Information
25.	Iout	1.5 A	System	Iout operating point
				Information
26.	Mode	BOOST PWM CCM	System	PWM/PFM Mode
				Information
27.	Pout	7.5 W	System	Total output power
				Information
28.	Rload_crit	40.9 Ohm	System	Minimum Rload required during Start up
				Information
29.	Total BOM	\$2.29	System	Total BOM Cost
				Information
30.	Vin	4.0 V	System	Vin operating point
				Information
31.	Vout Actual	4.984 V	System	Vout Actual calculated based on selected voltage divider resistors
				Information
32.	Vout Tolerance	1.696 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
				Information
33.	Vout p-p	4.723 mV	System	Peak-to-peak output ripple voltage
				Information

## Design Inputs

Name	Value	Description
Iout	1.5	Maximum Output Current

Name	Value	Description
VinMax	16.0	Maximum input voltage
VinMin	4.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	TPS63070	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 4.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### Design Assistance

1. Master key : 80160103AF850990F4D022DBE06DCD90[v1]
2. **TPS63070** Product Folder : <http://www.ti.com/product/TPS63070> : contains the data sheet and other resources.

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